



常州飞尔泰半导体科技有限公司

SOD-123 贴片塑封稳压二极管

SOD-123 Plastic-Encapsulate Zener Diode

特征 Features

SOD-123



- 齐纳击穿阻抗低; Low Zener Impedance
- 最大功率耗散 500mW; Power Dissipation of 500mW
- 高稳定性和可靠性。High Stability and High Reliability

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25 ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
功率消耗 Power Dissipation	Pd	500 ¹⁾	mW
正向压降 Forward Voltage @IF=10mA	Vf	0.9 ²⁾	V
存储温度 Storage temperature range	Ts	-65-+150	

1) Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm²

2) Short duration test pulse used to minimize self-heating effect

3) f=1KHz

电特性 (TA = 25 除非另有规定)

Electrical Characteristics (Ratings at 25 ambient temperature unless otherwise specified).

型号	印字 (代码)	Vz1(@Izt)		Izt	Zzt@Izt	Zzk		IR	
		Min (V)	Max (V)			Max	Izk	Max uA	VR V
MMSZ5221B	C1	2.28	2.52	20	30	1200	0.25	100	1.0
MMSZ5223B	C3	2.57	2.84	20	30	1300	0.25	75	1.0
MMSZ5225B	C5	2.85	3.15	20	30	1600	0.25	50	1.0
MMSZ5226B	G1	3.14	3.47	20	28	1600	0.25	25	1.0
MMSZ5227B	G2	3.42	3.78	20	24	1700	0.25	15	1.0
MMSZ5228B	G3	3.71	4.10	20	23	1900	0.25	10	1.0
MMSZ5229B	G4	4.09	4.52	20	22	2000	0.25	5.0	1.0
MMSZ5230B	G5	4.47	4.94	20	19	1900	0.25	5.0	2.0
MMSZ5231B	E1	4.85	5.36	20	17	1600	0.25	5.0	2.0
MMSZ5232B	E2	5.32	5.88	20	11	1600	0.25	5.0	3.0
MMSZ5233B	E3	5.70	6.30	20	7	1600	0.25	5.0	3.5
MMSZ5234B	E4	5.89	6.51	20	7	1000	0.25	5.0	4.0
MMSZ5235B	E5	6.46	7.14	20	5	750	0.25	3	5.0
MMSZ5236B	F1	7.13	7.88	20	6	500	0.25	3	6.0
MMSZ5237B	F2	7.79	8.61	20	8	500	0.25	3	6.5
MMSZ5238B	F3	8.27	9.14	20	8	600	0.25	3	6.5
MMSZ5239B	F4	8.65	9.56	20	10	600	0.25	3	7.0
MMSZ5240B	F5	9.50	10.50	20	17	600	0.25	3	8.0

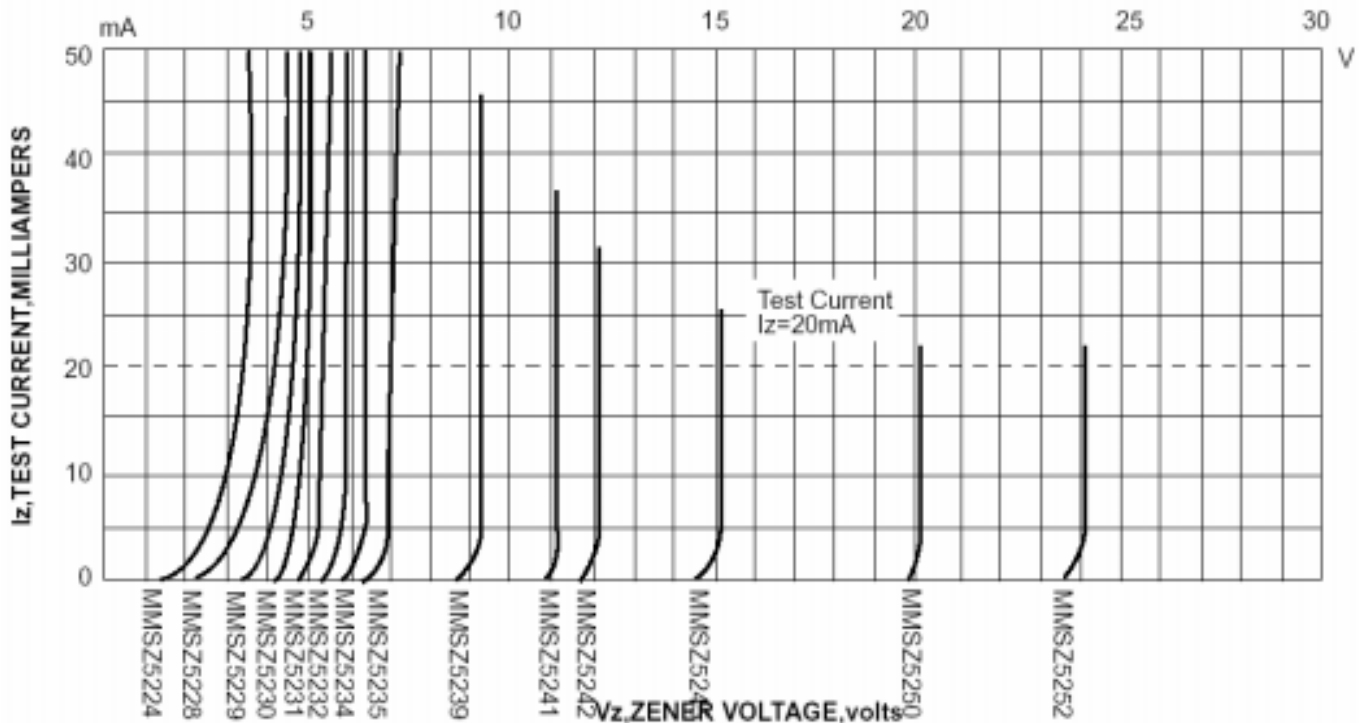


MMSZ5221B- MMSZ 5259B Series

型号	印字 (代码)	Vz1(@Izt)			Zzt@Izt	Zzk		IR	
		Min (V)	Max (V)	Izt mA	Max	Max	Izk mA	Max uA	VR V
MMSZ5241B	H1	10.45	11.55	20	22	600	0.25	2.0	8.4
MMSZ5242B	H2	11.40	12.60	20	30	600	0.25	1.0	9.1
MMSZ5243B	H3	12.35	13.65	9.5	13	600	0.25	0.5	9.9
MMSZ5244B	H4	13.30	14.70	9.0	15	600	0.25	0.1	10
MMSZ5245B	H5	14.25	15.75	8.5	16	600	0.25	0.1	11
MMSZ5246B	J1	15.20	16.80	7.8	17	600	0.25	0.1	12
MMSZ5248B	J3	17.10	18.90	7.0	21	600	0.25	0.1	14
MMSZ5250B	J5	19.00	21.00	6.2	25	600	0.25	0.1	15
MMSZ5251B	K1	20.90	23.10	5.6	29	600	0.25	0.1	17
MMSZ5252B	K2	22.80	25.20	5.2	33	600	0.25	0.1	18
MMSZ5253B	K3	23.75	26.25	5.0	35	600	0.25	0.1	19
MMSZ5254B	K4	25.65	28.35	5.0	41	600	0.25	0.1	21
MMSZ5255B	K5	26.60	29.40	4.5	44	600	0.25	0.1	21
MMSZ5256B	M1	28.50	31.50	4.2	49	600	0.25	0.1	23
MMSZ5257B	M2	31.35	34.65	3.8	58	700	0.25	0.1	25
MMSZ5258B	M3	34.20	37.80	3.4	70	700	0.25	0.1	27
MMSZ5259B	M4	37.05	40.95	3.2	80	800	0.25	0.1	30

VF≤0.9V@IF=10mA

Breakdown characteristics





MMSZ5221B- MMSZ 5259B Series

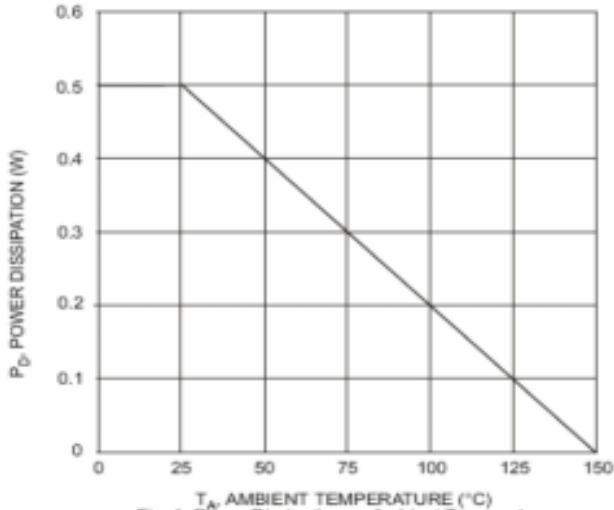


Fig. 1 Power Dissipation vs Ambient Temperature

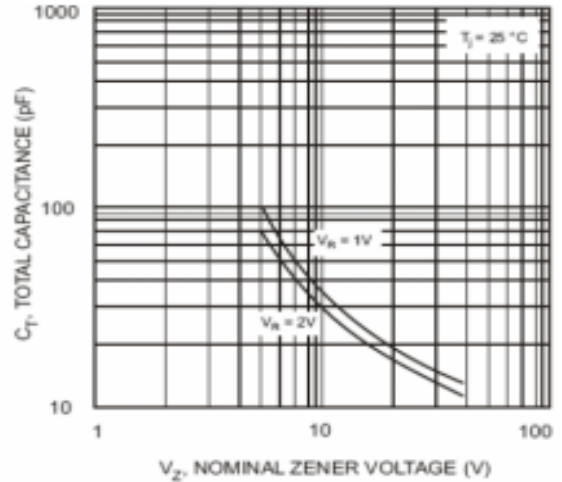


Fig. 2 Total Capacitance vs Nominal Zener Voltage

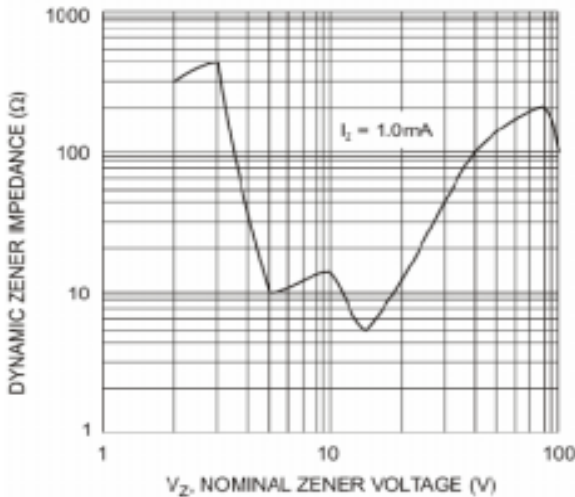
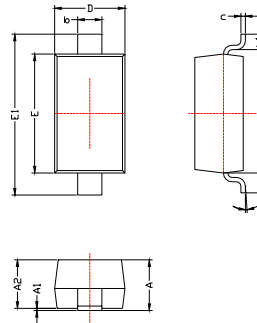


Fig. 3 Zener Voltage vs. Zener Impedance

SOD-123 PACKAGE OUTLINE

Plastic surface mounted package

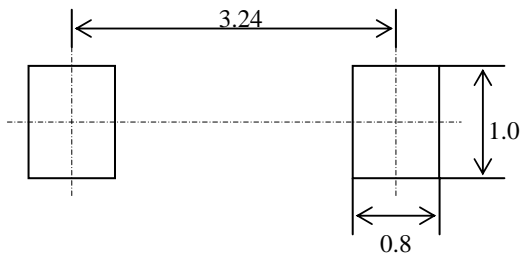


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
	0°	8°

焊盘设计参考

Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



- 中心距: 3.24
- 脚宽: 0.55
- 焊盘宽: 1.00
- 脚长: 0.50
- 焊盘长: 0.80

技术要求:

- 1, 塑封体尺寸: 2.70 X 1.60
- 2, 未注公差为: ±0.05
- 3, 所有单位: mm